

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. NAKAMURA, et al.
Serial No.: 10/500,119
Filed: JUNE 17, 2005
For: CONNECTION BOARD, AND MULTI-LAYER WIRING BOARD,
SUBSTRATE FOR SEMICONDUCTOR PACKAGE AND
SEMICONDUCTOR PACKAGE USING CONNECTION
BOARD, AND MANUFACTURING METHOD THEREOF
Group AU: 2841
Examiner: Ishwarbhai B Patel
Confirm. No: 7910

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Mail Stop: AMEND – NO FEE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

January 14, 2008

Sir:

In response to the Notice of Non-compliant Amendment mailed December 12, 2007, please replace the “**Amendments to the Claims**” section of the Amendment filed October 11, 2007, with the following “**Amendments to the Claims**” section.